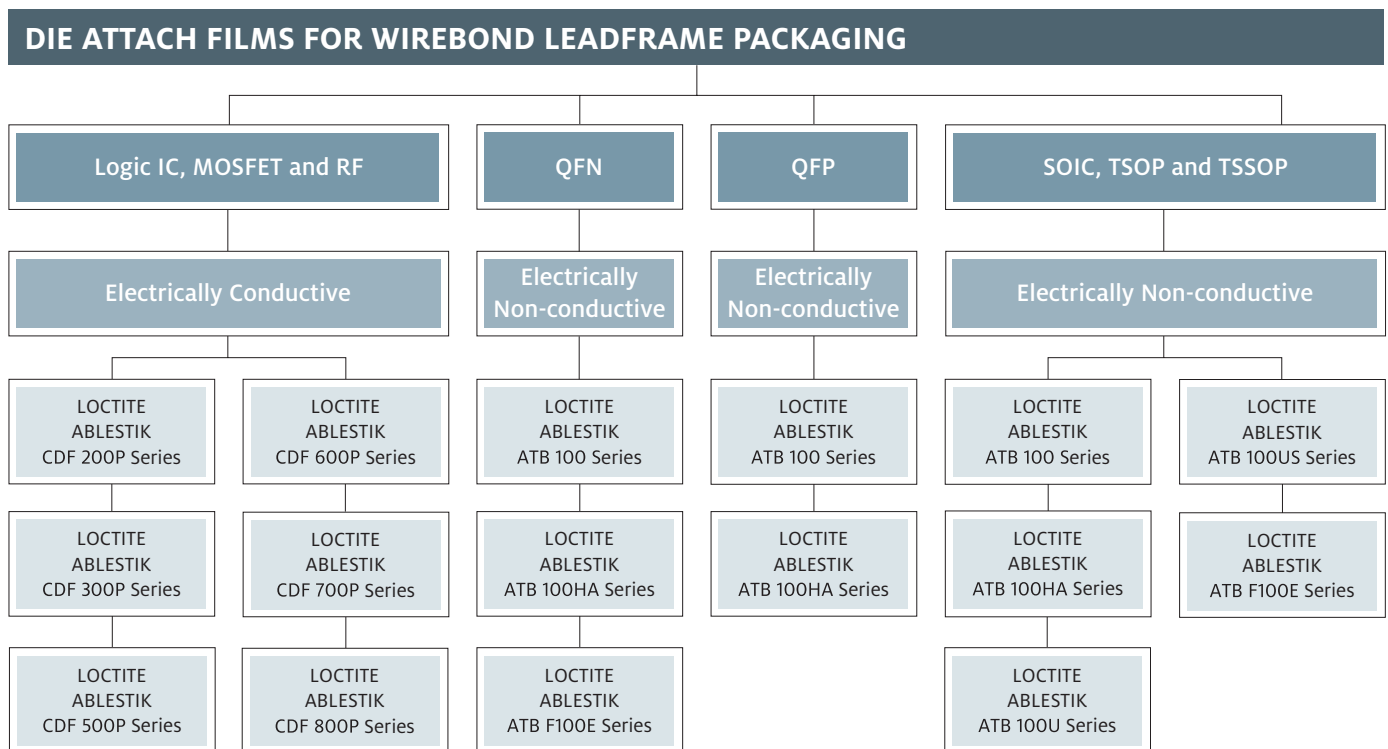


Henkel Solutions for Leadframe Packaging

Die Attach Films





Henkel Solutions for Leadframe Packaging Die Attach Films

ELECTRICALLY CONDUCTIVE DIE ATTACH FILMS (CDAF)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	FILM THICKNESS (µm)	MOISTURE SENSITIVITY LEVEL, MSL	THERMAL CONDUCTIVITY (W/m·K)	IN-PACKAGE THERMAL RESISTANCE (K/W)
LOCTITE ABLESTIK CDF 200P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Suitable for small die Recommended for thin wafer handling applications Oven cure 	15 or 30	L1 260°C capable	2.3	1.5
LOCTITE ABLESTIK CDF 300P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Suitable for small die High adhesion Good wetting Oven cure 	15 or 30	L1 260°C capable	1.0	2.1
LOCTITE ABLESTIK CDF 500P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Suitable for medium to large dies Good wetting and low warpage Recommended for thin wafer handling applications Oven cure 	15 or 30	L1 260°C capable	1.5	1.4
LOCTITE ABLESTIK CDF 600P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Low stress and excellent wetting for large die Compatible with various metal surfaces, including solder Recommended for thin wafer handling applications Oven cure 	25	L2 260°C capable	1.0	2.1
LOCTITE ABLESTIK CDF 700P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Suitable for small and medium die High adhesion Oven cure 	15 or 30	L1 260°C capable	5.5	0.7
LOCTITE ABLESTIK CDF 800P Series	Ag-filled die attach adhesive	<ul style="list-style-type: none"> Suitable for small die Recommended for thin wafer handling applications Oven cure 	15	L1 260°C capable	3.4	0.7

ELECTRICALLY NON-CONDUCTIVE DICING DIE ATTACH FILMS (DDF)

PRODUCT	DESCRIPTION	KEY ATTRIBUTES	DICING TAPE	FILM THICKNESS (µm)	WAFER THICKNESS (µm)	MOISTURE SENSITIVITY LEVEL, MSL	MODULUS AT 25°C (MPa)
LOCTITE ABLESTIK ATB 100 Series	Silica-filled, rubberized epoxy die attach adhesive	<ul style="list-style-type: none"> Compatible with Cu wire or Au wire packages Excellent wetting Compatible with Stealth Dicing Before Grind (SDBG) process Oven cure 	Non-UV	15, 20, 25 or 30	≥ 75	L2 260°C capable	1,170
LOCTITE ABLESTIK ATB 100HA Series	Silica-filled, epoxy die attach adhesive	<ul style="list-style-type: none"> Consistent dicing and die pickup for large die applications No passivation damage Compatible with Stealth Dicing Before Grind (SDBG) process SkipCure 	UV/Non-UV	5, 10, 15, 20, 25 or 30	≥ 50	L1 260°C capable	2,299
LOCTITE ABLESTIK ATB 100U Series	Silica-filled, rubberized epoxy die attach adhesive	<ul style="list-style-type: none"> Compatible with Cu wire or Au wire packages No passivation damage Compatible with Stealth Dicing Before Grind (SDBG) process Fast oven cure 	Non-UV	5, 10, 15, 20, 25 or 30	≥ 75	L2 260°C capable	875
LOCTITE ABLESTIK ATB 100US Series	Silica-filled, epoxy die attach adhesive	<ul style="list-style-type: none"> Consistent dicing and die pickup for large die applications No passivation damage Long thermal budget (4 hr. at 175°C) SkipCure during molding process 	UV/Non-UV	5, 10, 15, 20, 25 or 30	≥ 50	L2 260°C capable	1,277
LOCTITE ABLESTIK ATB F100E Series	Silica-filled, epoxy die attach adhesive	<ul style="list-style-type: none"> Suitable for small to large die Excellent workability for below 3 mm x 3 mm die Long work life (4 months before and after lamination) Compatible with Stealth Dicing Before Grind (SDBG) process Film over wire (FoW) and film over die (FoD) applications Oven cure 	UV/Non-UV	25 FoW: 35 – 80 FoD: 90 – 150	≥ 75	L1 260°C capable	5,256

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